

Amendments to the Specification

IN THE TITLE

Please change USPTO records to indicate that the title to be used in this application is --- IMIDAZOLE/ORGANIC MONOCARBOXYLIC ACID SALT DERIVATIVE REACTION PRODUCT, METHOD FOR PRODUCING THE SAME, AND SURFACE TREATMENT AGENT, RESIN ADDITIVE AND RESIN COMPOSITION USING THE SAME---, which title coincides with the title appearing in the English translation of the specification.

IN THE WRITTEN DESCRIPTION

Please replace paragraph [0003] with the following rewritten paragraph:

[0003] During the manufacturing process, the copper foil is bonded to the substrate, and they are heated, immersed in acidic or alkaline solutions, ~~applied~~ a resist ink applied thereto, soldered, and hence the copper foil and the substrate are required to have various properties. To satisfy these requirements, with regard to the copper foil, studies have been carried out ~~intely~~ by subjecting the copper foil to brass layer formation treatment (Japanese Patent Publication Nos. S51-35711 and S54-6701), chromate treatment, zinc-chromium mixture coating treatment in which the coating includes zinc or zinc oxide and chromium oxide (Japanese Patent Publication No. S58-7077), treatment with a silane coupling agent, and the like. Moreover, with regard to the resin, the requirements are satisfied by changing the type of resin and/or curing agent and/or the mixing proportions thereof, by adding additives, and so on. Moreover, in the case of glass fiber, surface treatments using a silane coupling agent or the like have been studied. However, in recent years, there have been advances in miniaturization of printed circuits, and the

properties required of the boards used in electronic devices have become ever more stringent.

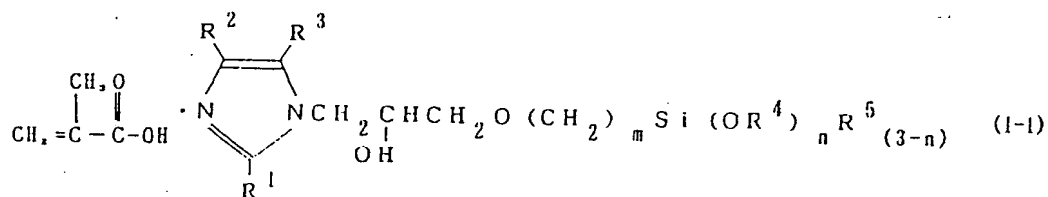
Please replace paragraph [0005] with the following rewritten paragraph:

[0005] Moreover, a composite material in which an inorganic material such as silica or alumina is filled into an epoxy resin matrix is used as an electrically insulating casting material used, for example, in high voltage / high capacity devices and in sealing semiconductors in power plants. Various electrical and mechanical properties are required of such a material, and to satisfy these requirements it is necessary to improve the adhesion between the inorganic material and the resin. Measures such as adding a silane coupling agent into the resin or subjecting the inorganic material to surface treatment with a silane coupling agent have been proposed, but ~~yet~~ further improvement of the resin / inorganic material interface is required.

Please replace paragraph [0021] with the following rewritten paragraph:

[0021] Imidazole 13.62g (0.2mol) was melted at 95°C, and 47.27g (0.2mol) of 3-glycidoxypropyltrimethoxysilane was instilled therein over 30 minutes while stirring under an argon atmosphere. After the instillation had been completed, the reaction was continued for a further 1 hour at a temperature of 95°C, thus obtaining imidazole-silane compounds. The reaction solution was then kept at a temperature of 80°C while instilling therein 17.2g (0.2mol) of methacrylic acid over 30 minutes. After the instillation had been completed, the reaction was ~~proceeded~~ allowed to proceed for a further 30 minutes at a temperature of 80°C, thus obtaining a reaction product containing the compound

represented by undermentioned formula (1-1) along with other complex compounds having siloxane bonds. The reaction product was obtained as a viscous transparent orange liquid. The ^1H -NMR spectrum, ^{13}C -NMR spectrum, ^{29}Si -NMR spectrum and FT-IR spectrum of the obtained imidazole / methacrylic acid salt derivative are shown in Figs. 1, 2, 3 and 4, respectively.



(Example 2)